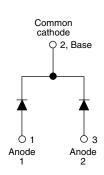
VS-HFA16PA60C-N3

Vishay Semiconductors

HEXFRED[®] Ultrafast Soft Recovery Diode, 2 x 8 A



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PRIMARY CHARACTERISTICS								
I _{F(AV)} 2 x 8 A								
V _R	600 V							
V _F at I _F	1.4 V							
t _{rr} typ.	18 ns							
T _J max.	150 °C							
Package	TO-247AC 3L							
Circuit configuration	Common cathode							

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

DESCRIPTION

VS-HFA16PA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16PA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16PA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V _R		600	V					
Maximum continuous forward current	I_	T _C = 100 °C	8						
per device	l _F	1 <u>C</u> = 100 O	16	А					
Single pulse forward current	I _{FSM}	t _p = 10 ms	60	A					
Maximum repetitive forward current	I _{FRM}		24						
Maximum power dissipation	PD	$T_{C} = 25 \ ^{\circ}C$	36	W					
Maximum power dissipation	۳D	T _C = 100 °C	14	vv					
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C					

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Document Number: 94056

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RoHS COMPLIANT HALOGEN FREE

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ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25 \text{ °C}$ unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	600	-	-				
		I _F = 8.0 A		-	1.4	1.7	V		
Maximum forward voltage	V _{FM}	I _F = 16 A	See fig. 1	-	1.7	2.1			
		$I_F = 8.0 \text{ A}, T_J = 125 \text{ °C}$		-	1.4	1.7			
Maximum reverse		$V_{R} = V_{R}$ rated	See fig. 2	-	0.3	5.0			
leakage current		T_J = 125 °C, V_R = 0.8 x V_R rated	See fig. 2	-	100	500	μA		
Junction capacitance	CT	V _R = 200 V See fig. 3		-	10	25	pF		
Series inductance	L _S	Measured lead to lead 5 mm from p	-	8.0	-	nH			

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time See fig. 5, 6 and 16	t _{rr}	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200$	A/μs, V _R = 30 V	-	18	-	ns	
	t _{rr1}	T _J = 25 °C	I _F = 8.0 A dI _F /dt = 200 A/μs V _R = 200 V	-	37	55		
	t _{rr2}	T _J = 125 °C		-	55	90		
Peak recovery current See fig. 7 and 8	I _{RRM1}	T _J = 25 °C		-	3.5	5.0	A	
	I _{RRM2}	T _J = 125 °C		-	4.5	8.0		
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	65	138		
See fig. 9 and 10	Q _{rr2}	T _J = 125 °C		-	124	360	ne	
Peak rate of fall recovery current during t_b See fig. 11 and 12	dl _{(rec)M} /dt1	T _J = 25 °C		-	240	-	A∕µs	
	dl _{(rec)M} /dt2	T _J = 125 °C		-	210	-	Λµs	

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Junction to case, single leg conducting			-	-	3.5			
Junction to case, both leg conducting	R _{thJC}		-	-	1.75	к/w		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	40			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.25	-			
Waight			-	6.0	-	g		
Weight			-	0.21	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-247AC 3L	HFA16PA60C					

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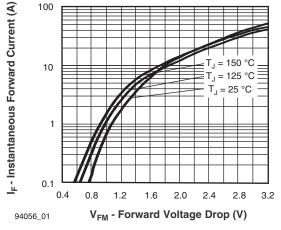


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

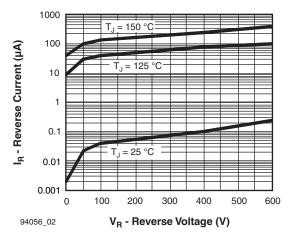


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

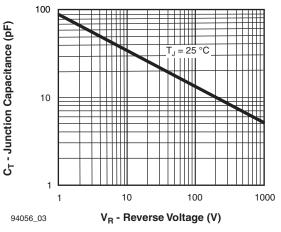
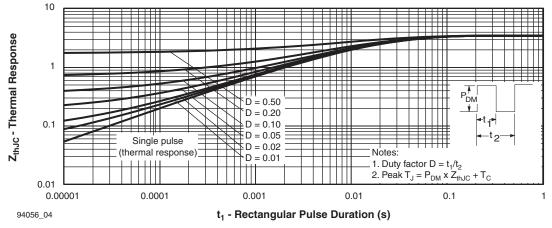


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)





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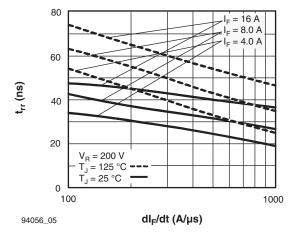


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

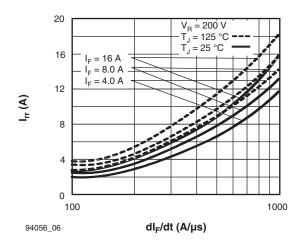


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

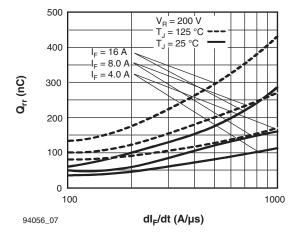


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

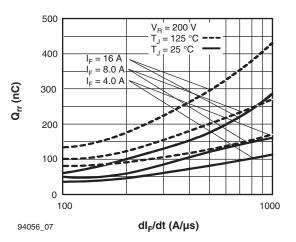


Fig. 8 - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)

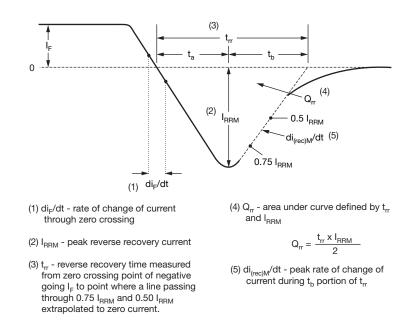


Fig. 9 - Reverse Recovery Waveform and Definitions

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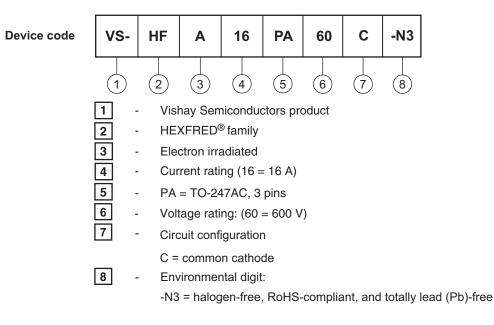
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ORDERING INFORMATION TABLE



ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-HFA16PA60C-N3	25	500	Antistatic plastic tube						

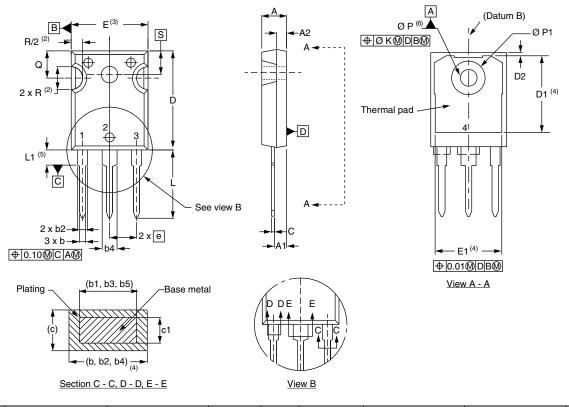
LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?96138</u>						
Part marking information	www.vishay.com/doc?95007					
SPICE model	www.vishay.com/doc?96596					



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TO-247AC 3L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES	SYMBOL		MILLIN	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
A	4.65	5.31	0.183	0.209			D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102			Е	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054			E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055			е	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053			ØК	0.2	254	0.0)10	
b2	1.65	2.39	0.065	0.094			L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092			L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135			ØР	3.56	3.66	0.14	0.144	
b5	2.59	3.38	0.102	0.133			Ø P1	-	7.39	-	0.291	
С	0.38	0.89	0.015	0.035			Q	5.31	5.69	0.209	0.224	
c1	0.38	0.84	0.015	0.033			R	4.52	5.49	0.178	0.216	
D	19.71	20.70	0.776	0.815	3		S	5.51	BSC	0.217	BSC	
D1	13.08	-	0.515	-	4							

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5M-1994

(2) Contour of slot optional

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

(4) Thermal pad contour optional with dimensions D1 and E1

⁽⁵⁾ Lead finish uncontrolled in L1

⁽⁶⁾ Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-247 with exception of dimension Q

Revision: 20-Jun-17

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